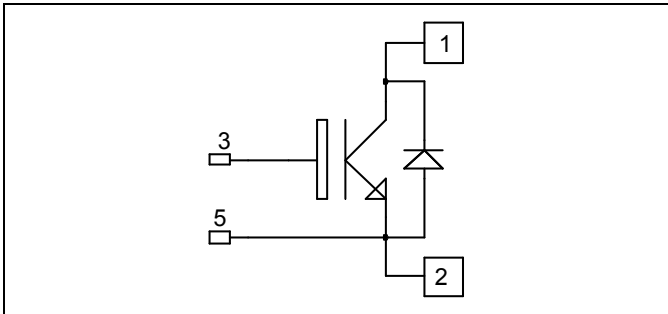


**Single switch
Trench + Field Stop IGBT
Power Module**

**$V_{CES} = 1700V$
 $I_C = 600A @ T_c = 80^\circ C$**



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

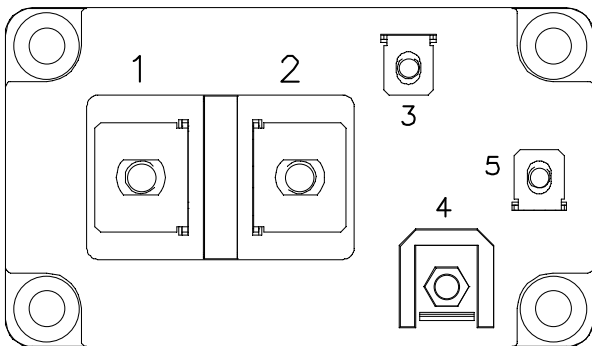
Features

- Trench + Field Stop IGBT Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated

- Kelvin emitter for easy drive
- M6 connectors for power
- M4 connectors for signal
- High level of integration

Benefits

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CESat}
- RoHS Compliant



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage	1700	V
I_C	Continuous Collector Current	$T_C = 25^\circ C$	1100
		$T_C = 80^\circ C$	600
I_{CM}	Pulsed Collector Current	$T_C = 25^\circ C$	1200
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Maximum Power Dissipation	$T_C = 25^\circ C$	2900
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^\circ C$	1200A@1600V

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}, V_{CE} = 1700\text{V}$			5	mA
$V_{CE(sat)}$	Collector Emitter saturation Voltage	$V_{GE} = 15\text{V}$ $I_C = 600\text{A}$	$T_j = 25^\circ\text{C}$	2.0	2.4	V
			$T_j = 125^\circ\text{C}$	2.4		
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 24\text{ mA}$	5.2	5.8	6.4	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}, V_{CE} = 0\text{V}$			400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0\text{V}, V_{CE} = 25\text{V}$		51		nF
C_{res}	Reverse Transfer Capacitance	$f = 1\text{MHz}$		1.8		
Q_G	Gate charge	$V_{GE} = \pm 15\text{V}, I_C = 600\text{A}$ $V_{CE} = 900\text{V}$		6.8		μC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 900\text{V}$ $I_C = 600\text{A}$ $R_G = 2.4\Omega$		280		ns
T_r	Rise Time			100		
$T_{d(off)}$	Turn-off Delay Time			850		
T_f	Fall Time			150		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 900\text{V}$ $I_C = 600\text{A}$ $R_G = 2.4\Omega$		330		ns
T_r	Rise Time			100		
$T_{d(off)}$	Turn-off Delay Time			1000		
T_f	Fall Time			230		
E_{on}	Turn On Energy	$V_{GE} = \pm 15\text{V}$ $V_{Bus} = 900\text{V}$	$T_j = 125^\circ\text{C}$	200		mJ
E_{off}	Turn Off Energy	$I_C = 600\text{A}$ $R_G = 2.4\Omega$	$T_j = 125^\circ\text{C}$	190		
I_{sc}	Short Circuit data	$V_{GE} \leq 15\text{V}; V_{Bus} = 1000\text{V}$ $t_p \leq 10\mu\text{s}; T_j = 125^\circ\text{C}$		2200		A

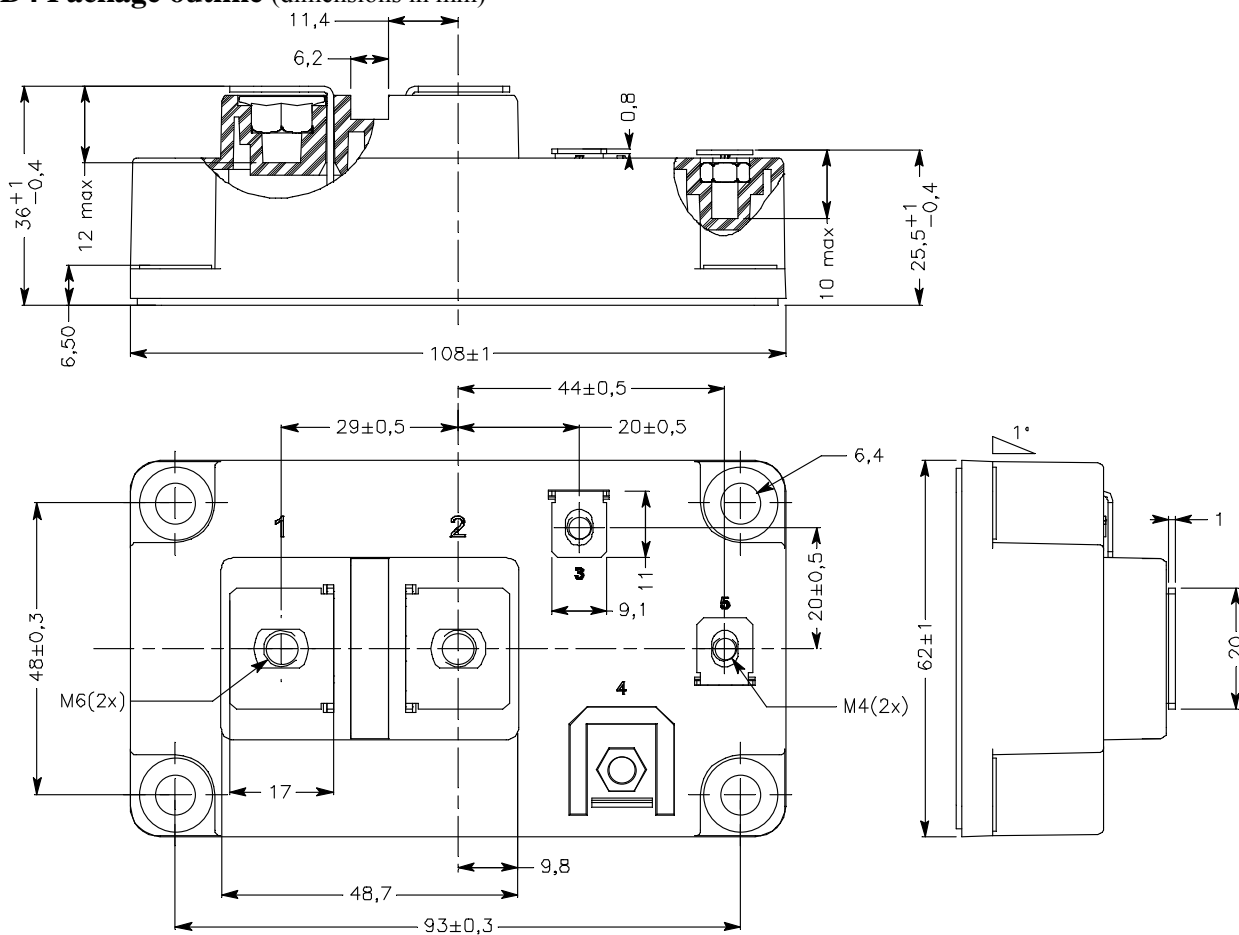
Reverse diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		1700			V
I_{RRM}	Maximum Reverse Leakage Current	$V_R = 1700\text{V}$	$T_j = 25^\circ\text{C}$		750	μA
			$T_j = 125^\circ\text{C}$		1000	
I_F	DC forward current		$T_C = 80^\circ\text{C}$	600		A
V_F	Diode Forward Voltage	$I_F = 600\text{A}$ $V_{GE} = 0\text{V}$	$T_j = 25^\circ\text{C}$	1.8	2.2	V
			$T_j = 125^\circ\text{C}$	1.9		
E_{rr}	Reverse Recovery Energy	$I_F = 600\text{A}$ $V_R = 900\text{V}$ $di/dt = 5200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$	85		mJ
			$T_j = 125^\circ\text{C}$	145		
t_{rr}	Reverse Recovery Time		$T_j = 25^\circ\text{C}$	450		ns
			$T_j = 125^\circ\text{C}$	600		
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$	150		μC
			$T_j = 125^\circ\text{C}$	250		

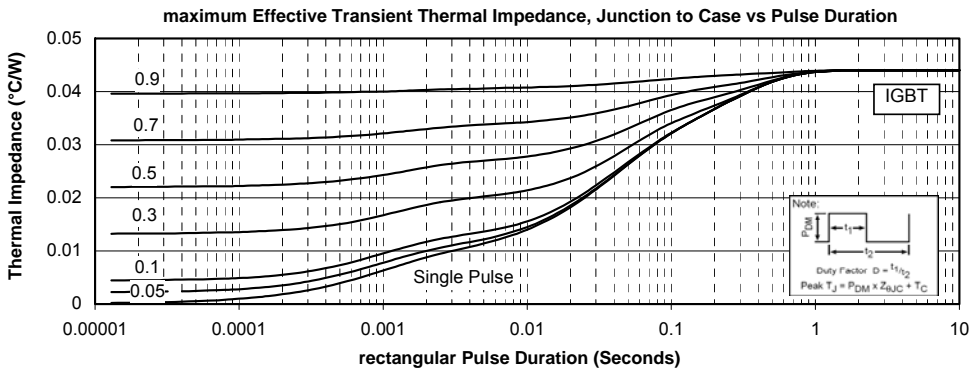
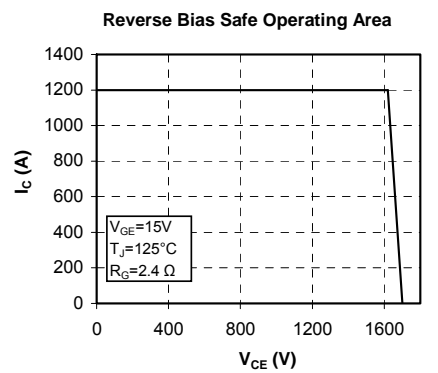
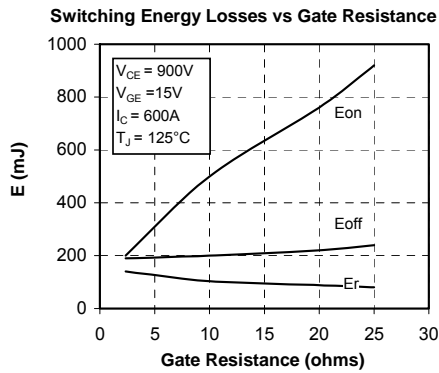
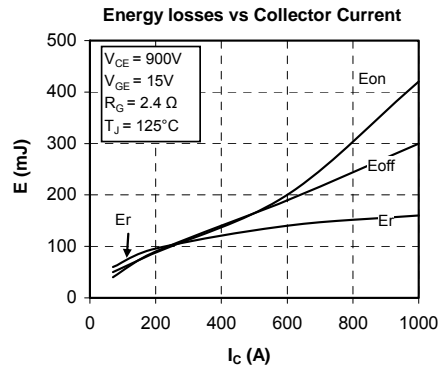
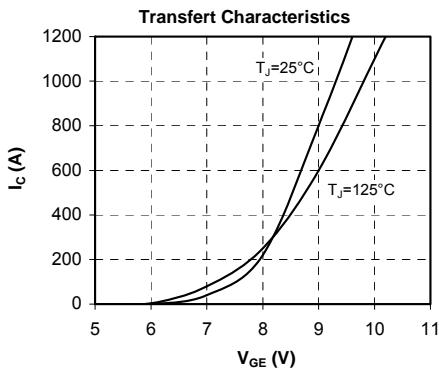
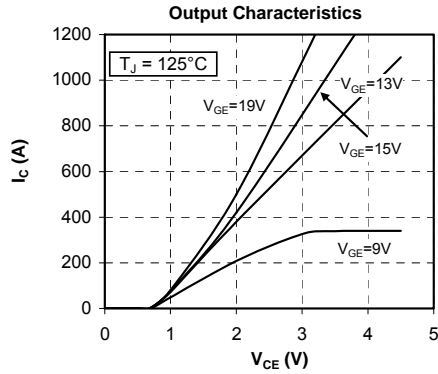
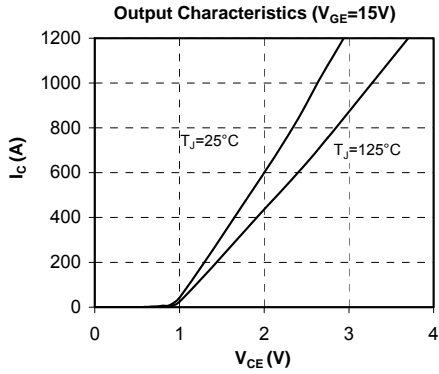
Thermal and package characteristics

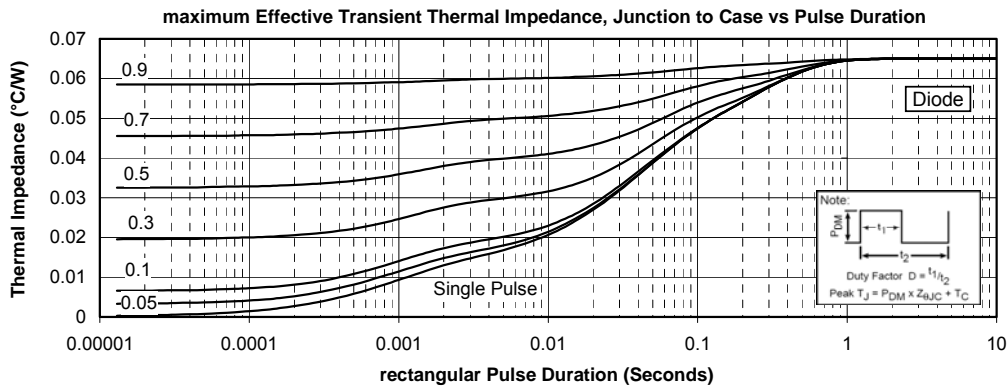
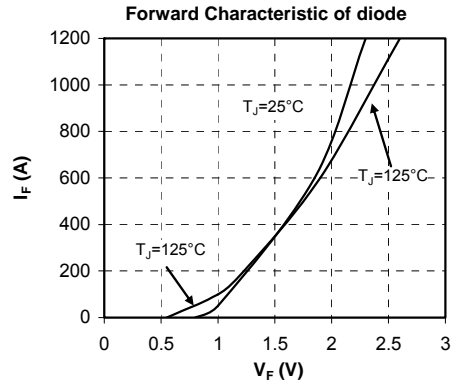
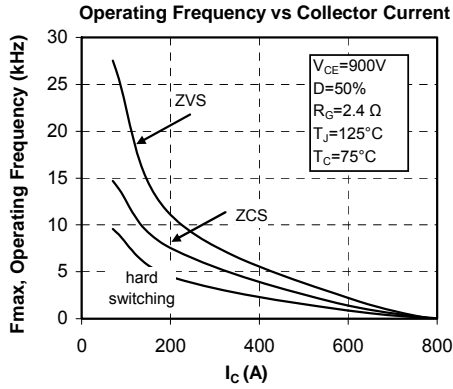
Symbol	Characteristic	Min	Typ	Max	Unit
R _{thJC}	Junction to Case Thermal Resistance	IGBT		0.044	°C/W
		Diode		0.065	
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, I _{isol} < 1mA, 50/60Hz	3500			V
T _J	Operating junction temperature range	-40		150	°C
T _{STG}	Storage Temperature Range	-40		125	
T _C	Operating Case Temperature	-40		125	
Torque	Mounting torque	M4	1	2	N.m
		M6	3	5	
Wt	Package Weight			350	g

D4 Package outline (dimensions in mm)



Typical Performance Curve





Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 6,939,743 7,352,045 5,283,201 5,801,417 5,648,283 7,196,634 6,664,594 7,157,886 6,939,743 7,342,262 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.